

L Number	Hits	Search Text	DB	Time stamp
1	191482	204/212.ccls. and pad or brush	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/26 12:58
7	398325	(204/212.ccls. and pad or brush) and cylindrical adj electrode or anode or cathode	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/26 11:34
13	25390	((204/212.ccls. and pad or brush) and cylindrical adj electrode or anode or cathode) and strips	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/26 11:39
19	115	((204/212.ccls. and pad or brush) and cylindrical adj electrode or anode or cathode) and strips and electropolishing	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/26 11:43
25	87	204/224R.ccls. and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/26 12:03
31	37	204/224M.ccls. and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/26 12:05
37	304335	204/224M.ccls. and pad and semiconductor or wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/26 12:23
43	19	204/224M.ccls. and pad and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/26 12:48
49	52	205/157.ccls. and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/26 12:49
55	8380	(204/212.ccls. and pad or brush) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/26 12:59
61	14	((204/212.ccls. and pad or brush) and semiconductor) and pad not brush	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/26 13:00